

Purpose

This declaration is intended to disclose substances contained in THAT Corporation's 4301x-I series integrated circuits. The table below lists Materials and Substances included in the Joint Industry Guide (JIG) - Material Composition Declaration Guide, released on September 19, 2003. This covers all materials defined in Article 4.1 of the European Directive 2002/95/EC on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS Directive).

Materials Declaration

Leadframe Plating: SnBi			Percent by weight of homogenous material ¹							
Controlled Chemicals		Threshold Limits		4301P	4301S	Shipping Container				
Cadmium	Elemental	0.01%	0.0075%, and not intentionally	ND ²	ND ²	ND	ND	ND	ND	
	Cd Compounds			ND	ND	ND	ND	ND	ND	
Lead	Elemental	0.10%	0.10%, and not intentionally added	ND	ND	ND	ND	ND	ND	
	Pb Compounds			ND	ND	ND	ND	ND	ND	
Mercury	Elemental			ND	ND	ND	ND	ND	ND	
	Hg Compounds			ND	ND	ND	ND	ND	ND	
Hexavalent Chromium	Elemental			ND	ND	ND	ND	ND	ND	
	Cr ₆ Compounds			ND	ND	ND	ND	ND	ND	
Polybrominated biphenyls (PBB)				ND	ND	ND	ND	ND	ND	
Polybrominated diphenylethers (PBDE)				ND	ND	ND	ND	ND	ND	
Polychlorinated biphenyls (PCB)				Not Regulated	Not intentionally added	ND	ND	ND	ND	ND
Polychlorinated naphthalenes (PCN)						ND	ND	ND	ND	ND
Polychlorinated terphenyls (PCT)		ND	ND			ND	ND	ND		
Chlorinated parafins (CP)		ND	ND			ND	ND	ND		
Other Chlorinated Compounds		ND	ND			ND	ND	ND		
Azo Compounds		ND	ND			ND	ND	ND		
Tributyltin compounds		ND	ND			ND	ND	ND		
Triphenyltin compounds		ND	ND			ND	ND	ND		
Other brominated organic compounds		Not Regulated	0.01%			2.3	1.5	ND	ND	ND
Antimony						ND	ND	ND	ND	ND
Other antimony compounds				1.1	1.5	ND	ND	ND		
Asbestos				ND	ND	ND	ND	ND		
Polyvinyl chloride (PVC) and blends				ND	ND	ND	ND	<0.001% of Vinyl Chloride		

Notes

1. A material is homogeneous if its compound concentration (as % wt) is not changed by mechanical disjoining (cutting, grinding, etc.). For example, in an integrated circuit, the homogenous materials would be the ink, mold compound, gold wires, die, die attach epoxy, base lead frame material and lead frame surface finish. Laser-marked parts may not include ink.
2. ND - None Detected.

Disclaimer

This information has been collected from THAT Corporation's manufacturing facilities and our worldwide supply chain. To the best of our knowledge, it is correct as of the date indicated on this page. However, we cannot guarantee its completeness or accuracy as some information has been derived from data sources outside the company.